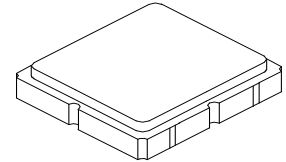


SF2656E

**455 MHz
SAW Filter**



SM3030-6

Electrical Characteristics

Maximum Ratings

Parameters Description	Unit	Minimum	Typical	Maximum
Operating Temperature Range	°C	-30	-	+80
Storage Temperature Range	°C	-40	-	+85
Maximum DC Voltage	V	-	-	0
Maximum Input Power	dBm	-	-	30
Source Impedance (single ended) ⁽¹⁾	Ω	-	50	-
Load Impedance (single ended) ⁽¹⁾	Ω	-	50	-
Package type & size	M			
Length x Width	mm	-	3.0 x 3.0	-
Height	mm	-	-	1.3
Moisture Sensitivity Level: 1	AEC-Q200 Qualified			

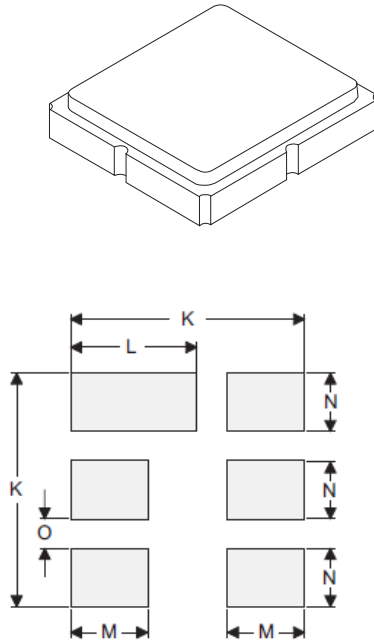
Electrical Specification

Parameters Description	Unit	Minimum	Typical	Maximum
Center Frequency (Fo)	MHz	-	455	-
Insertion Loss in 452.5 ~457.5 MHz	dB	-	2.2	2.8
Attenuation:				
0.3 ~ 443.0 MHz	dB	25	26	-
462.5 ~ 467.5 MHz	dB	30	47	-
467.5 ~ 1500.0 MHz	dB	25	28	-
1500.0 ~ 2000.0 MHz	dB	15	22	-
VSWR in 452.5 ~ 457.5 MHz	-	-	1.5	2.0

Notes : (1) No Matching Network .

SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

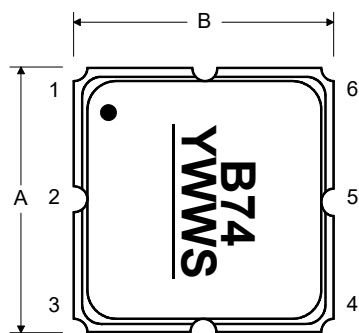
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

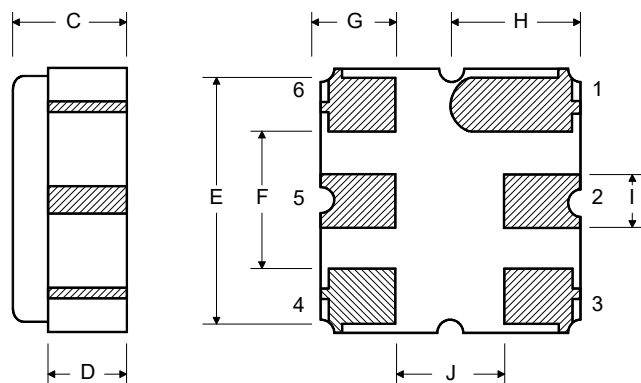
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW



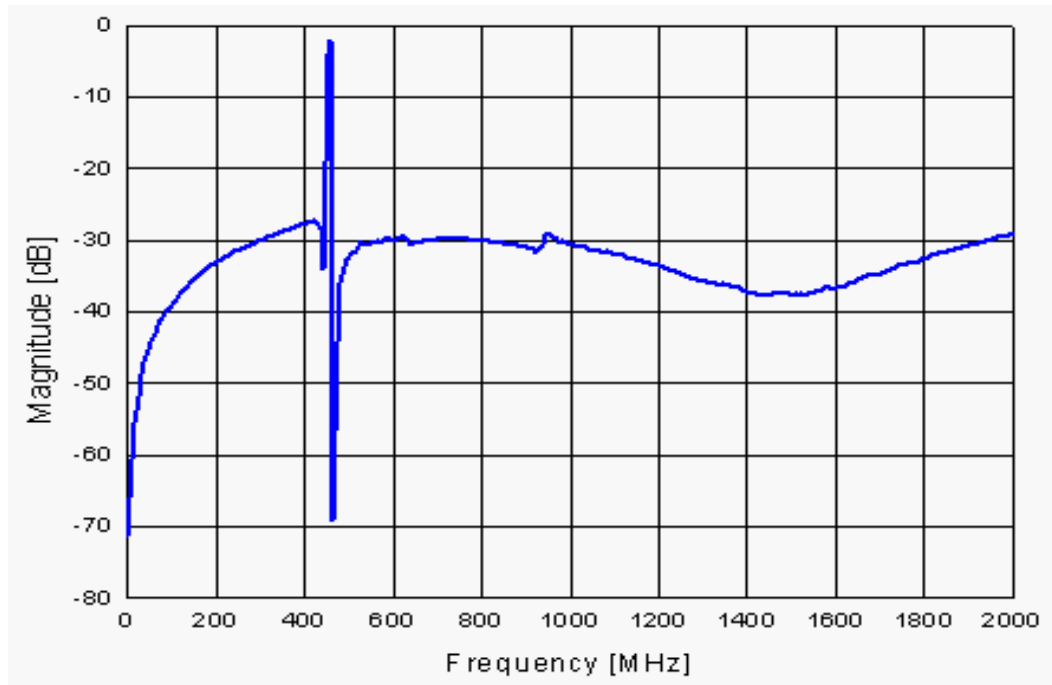
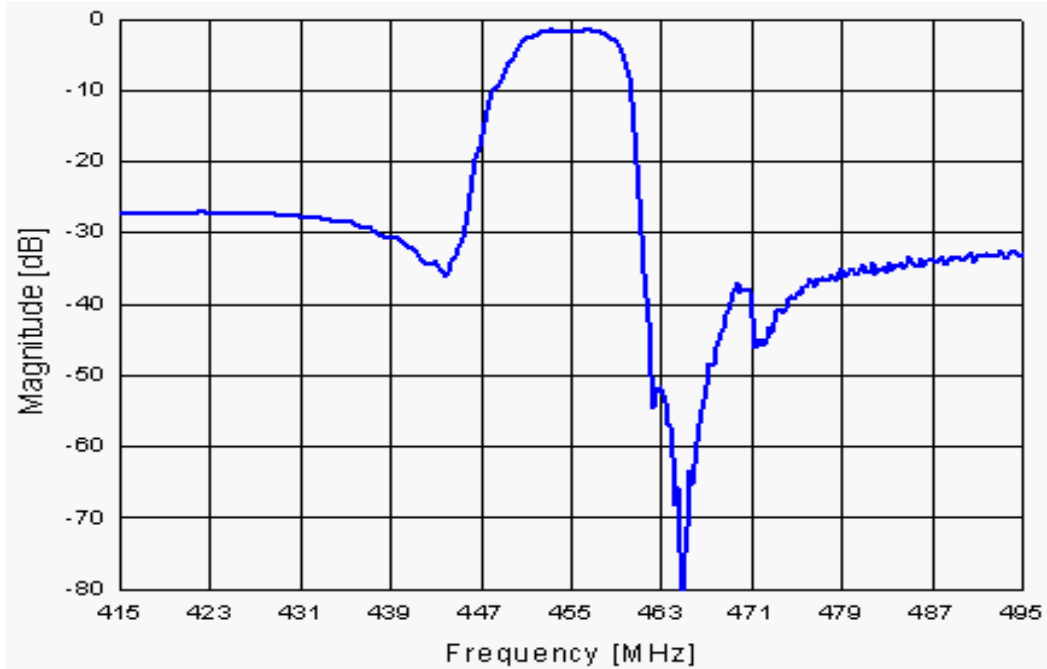
BOTTOM VIEW



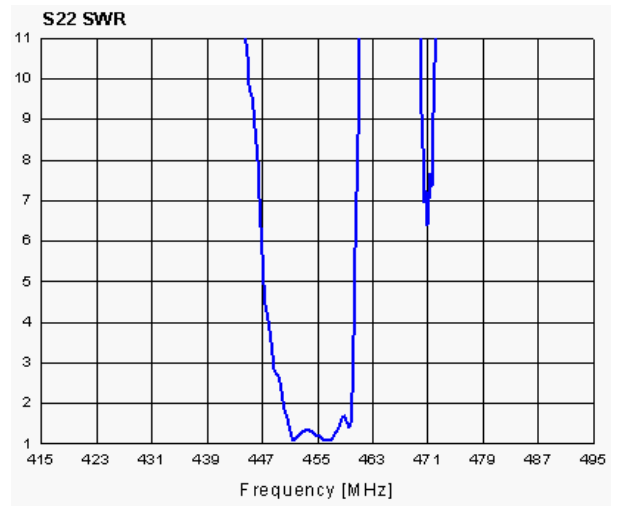
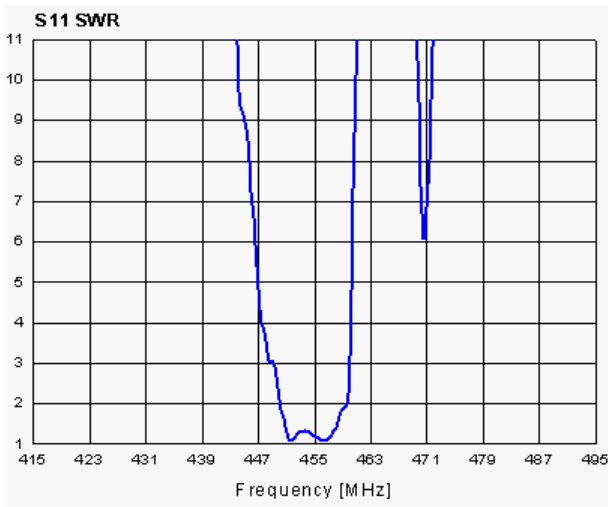
Pin 2 input
Pin 5 output
All other pins are ground

Frequency Characteristics

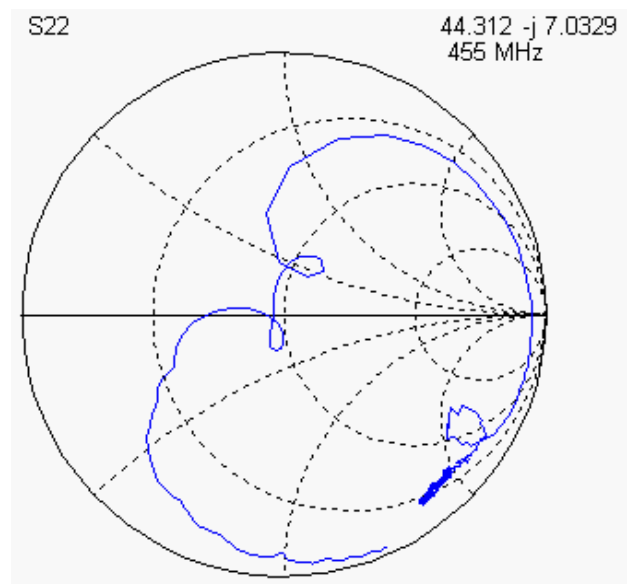
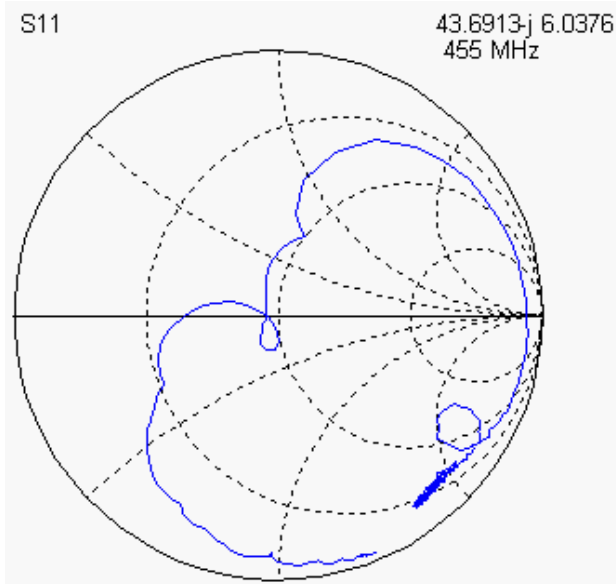
Frequency Response



VSWR



Smith Chart



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.